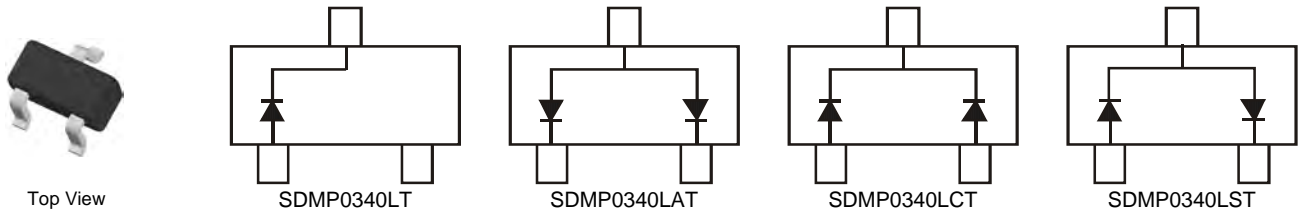


## Features

- Low Forward Voltage Drop
- Guard Ring Die Construction for Transient Protection
- Ideal for Low Logic Level Applications
- Low Capacitance
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device (Note 4 and 5)**

## Mechanical Data

- Case: SOT-523
- Case Material: Molded Plastic. UL Flammability Classification Rating: 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.002 grams (approximate)



## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>R(RM)</sub>	40	V
Working Peak Reverse Voltage	V <sub>R(WM)</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	28	V
Forward Continuous Current (Note 1)	I <sub>FM</sub>	30	mA
Non-Repetitive Peak Forward Surge Current @8.3ms Single half sine-wave superimposed on rated load	I <sub>FSM</sub>	200	mA

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	150	mW
Thermal Resistance, Junction to Ambient (Note 1)	R <sub>θJA</sub>	833	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-40 to +125	°C

## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	40	—	—	V	I <sub>R</sub> = 10μA
Forward Voltage Drop	V <sub>F</sub>	—	290	370	mV	I <sub>F</sub> = 1mA
Leakage Current (Note 2)	I <sub>R</sub>	—	—	1.0	μA	V <sub>R</sub> = 10V
Total Capacitance	C <sub>T</sub>	—	2	—	pF	V <sub>R</sub> = 1V, f = 1.0 MHz

- Notes:
1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

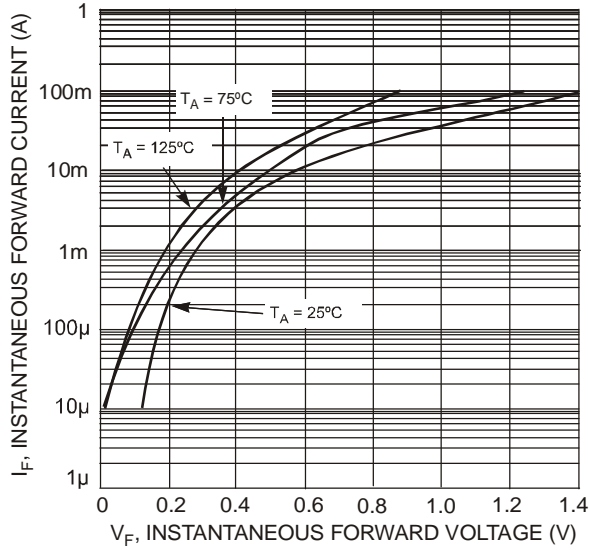


Fig. 1 Typical Forward Characteristics

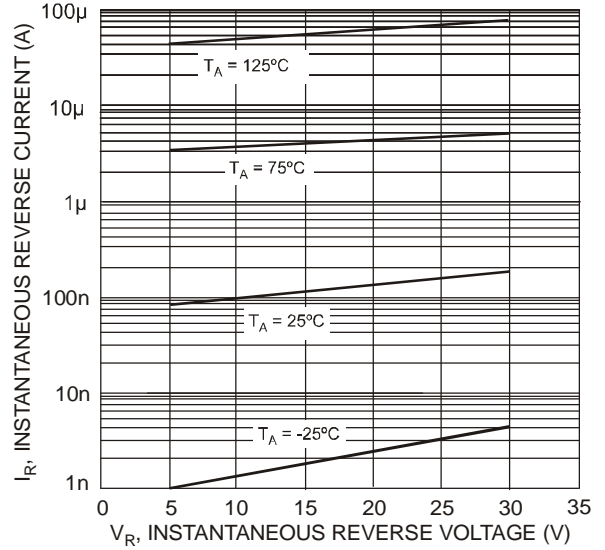


Fig. 2 Typical Reverse Characteristics

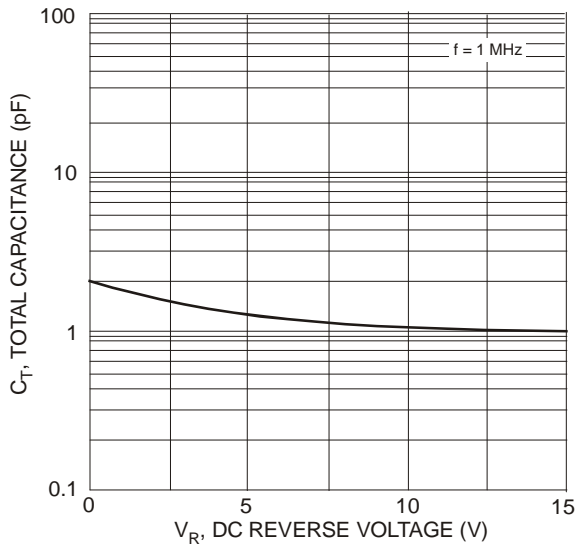


Fig. 3 Total Capacitance vs. Reverse Voltage

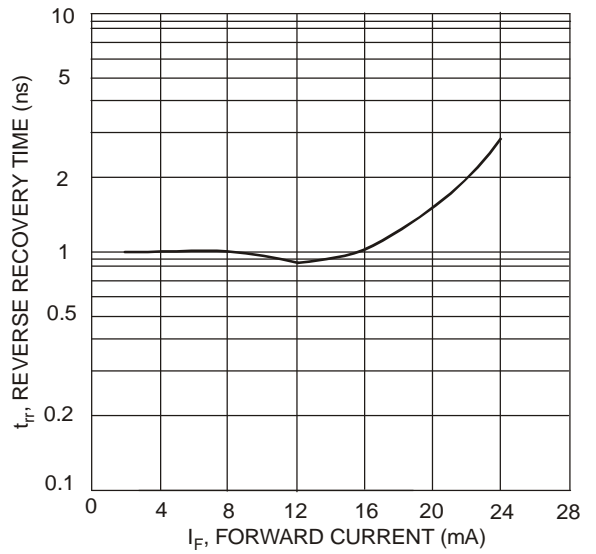


Fig. 4 Typical Reverse Recovery Time Characteristics

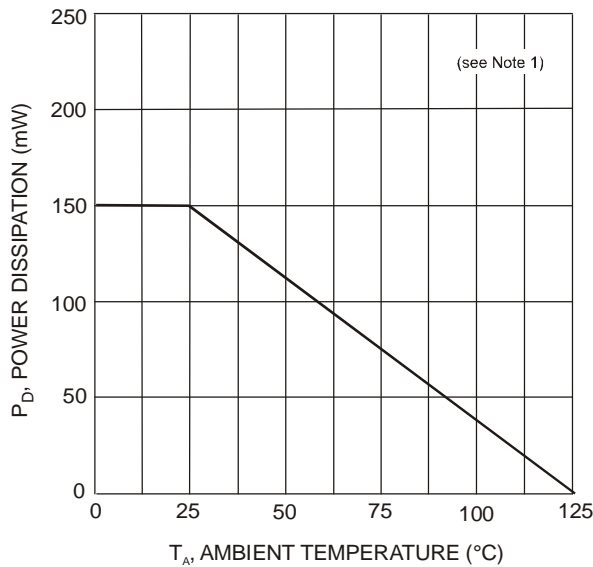


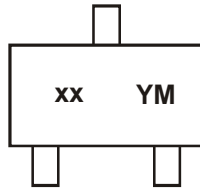
Fig. 5 Power Derating Curve

### Ordering Information (Note 6)

Device	Packaging	Shipping
SDMP0340LT-7-F	SOT-523	3000/Tape & Reel
SDMP0340LST-7-F	SOT-523	3000/Tape & Reel
SDMP0340LCT-7-F	SOT-523	3000/Tape & Reel
SDMP0340LAT-7-F	SOT-523	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

### Marking Information



xx = Product Type Marking Code  
 SM = SDMP0340LT  
 SQ = SDMP0340LAT  
 SP = SDMP0340LCT  
 SN = SDMP0340LST  
 YM = Date Code Marking  
 Y = Year (ex: N = 2002)  
 M = Month (ex: 9 = September)

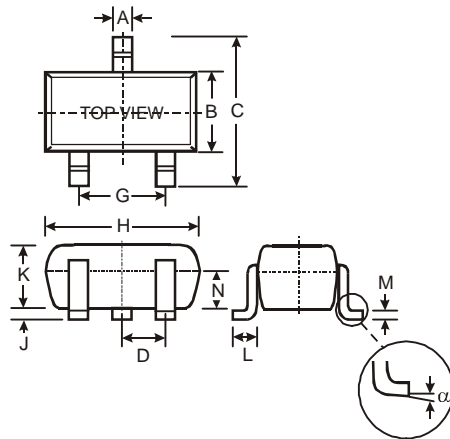
#### Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C

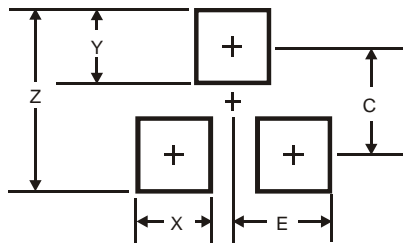
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

### Package Outline Dimensions



SOT-523			
Dim	Min	Max	Typ
A	0.15	0.30	0.22
B	0.75	0.85	0.80
C	1.45	1.75	1.60
D	—	—	0.50
G	0.90	1.10	1.00
H	1.50	1.70	1.60
J	0.00	0.10	0.05
K	0.60	0.80	0.75
L	0.10	0.30	0.22
M	0.10	0.20	0.12
N	0.45	0.65	0.50
$\alpha$	0°	8°	—
All Dimensions in mm			

### Suggested Pad Layout



Dimensions	Value (in mm)
Z	1.8
X	0.4
Y	0.51
C	1.3
E	0.7

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